MICROELECTRONIC STANDARDS (MS)

Contents

MS-001  Plastic DIP .300” Row Spacing
MS-002  Leadless Chip Carrier .050” Type A
MS-003  Leadless Chip Carrier .050” Type B
MS-004  Leadless Chip Carrier .050” Type C
MS-005  Leadless Chip Carrier .050” Type D
MS-006  Leaded Chip Carrier .050” Type A
MS-007  Leaded Chip Carrier .050” Type A
MS-008  Leaded Chip Carrier .050” Type B
MS-009  Leadless Chip Carrier .040”
MS-010  Plastic DIP .400” Row Spacing
MS-011  Plastic DIP .600” Row Spacing
MS-012  Plastic SO .150” Body Width
MS-013  Plastic SO .300” Body Width
MS-014  Single Layer Chip Carrier .040”
MS-015  Ceramic DIP .300” - .900” Spacing
MS-016  Plastic chip Carrier Rect. .050”
MS-017  Ceramic PGA .100” Pitch Cavity Down
MS-018  Square Plastic Chip Carrier .050” Pitch
MS-019  R-PDIP-T Dual in-line (Shrink .070”) Plastic Family .300” Row Spacing
MS-020  R-PDIP-T Dual in-line (Shrink .070”) Plastic Family .600” Row Spacing
MS-021  R-PDIP-T Dual in-line (Shrink .070”) Plastic Family .750” Row Spacing
MS-022  Metric Plastic Quad Flat Pack 1.0, 0.8, 0.65 mm
MS-023  Plastic SOJ
MS-024  TSOP II 10.16 mm Body
MS-025  Thin Small Outline Pkg. 7.62 mm Body
MS-026  Plastic Quad Flatpack 1.0 & 1.4 mm thick
MS-027  PDSO-J
MS-028  Rectangular Plastic Ball Grid Array 1.27 mm
MS-029  Fine Pitch QFP 2.6 mm footprint
MS-030  .300” wide CDIP
MS-031  .400” wide CDIP
MS-032  .600” wide CDIP
MS-033  Ceramic Dual Flatpack Family, .050”Pitch
MS-034  Plastic Square Ball Grid Array Family